

## PRODUCT DESCRIPTION:

AA-BOND PC12 is a two part bonding adhesive 100 percents solids, designed for coating most types of military printed circuit requirements.

Appearance	Clear to Amber
Cure Type	RT and Heat cure
Benefits	<ul style="list-style-type: none"> <li>• Continuous operation up to 123 °C</li> <li>• Meet military requirements</li> <li>• No Cracking over 1/8 "Diameter.</li> <li>• Non nutrient</li> </ul>
Mix Ratio by weight	100:80 / Resin: Hardener
Substrates	Most types of metals, aluminum, plastics, acrylic, or almost any thermoplastic substrate.
Operating Temperature	-20 to 125 °C
Typical Application	Automotive, Medical, Aerospace, Photonic, Assembly, industries, Also can be used anywhere that requires coating for circuits parts.

## UNCURED PROPERTIES:

Viscosity	Resin: 700 Cps at 25°C Hardener: 50000 CPS at 40°C
Density Lb/Gal	Resin : 9.44 Hardener: 8.3
Reactive solids contents, %	100
Pot Life	4 hours

## CURING SCHEDULE:

at room temperature	24 to 48 hours
65 °C	4 to 5 hours
75 °C	2 to 3 hours

## CURED ELECTRICAL PROPERTIES:

Insulation resistance, ohms (1-3 mil film) at 25 °C	1 x 10 <sup>14</sup>
Insulation resistance, ohms (1-3 mil film) at 65 °C 4 <sup>th</sup> cycle	0.5 x 10 <sup>10</sup>
Insulation resistance, ohms (1-3 mil film) at 65 °C 10 <sup>th</sup> cycle	0.5 x 10 <sup>10</sup>
Dielectric Constant 100Hz @25°C	5.39
Dielectric Constant 100KHz @25°C	4.15
Dielectric Strength volt/ mil	1,500
Dissipation Factor 100 Hz @25°C	0.11
Dissipation Factor 100 KHz @25°C	0.045
Volume Resistivity @25°C ohm-cm	1.0 x 10 <sup>14</sup>

## GENERAL INFORMATION:

For safe handling information on this product, consult the Safety Data Sheet (SDS).

## HOW TO USE:

1. Carefully clean and dry all surfaces to be bonded or coated
2. Warm Resin and Hardener to 30° - 40°C (86° - 104°F), then mix thoroughly and apply vacuum to remove the bubble with agitation (28 inches of mercury or better) for 5 to 10 minutes. Allow to stand for 30 minutes. Immerse the clean printed circuit board in AA-BOND PC12 at room temperature. The run-off is approximately 65 % to 70% resulting in 2 to 5 mil film thickness.
3. Some ingredients in this formulation provided may crystallize when subjected to low temperature storage. A gentle warming cycle of 52°C for 30 minutes prior to mixing components may be necessary.

## AVAILABILITY

This epoxy can be supplied in many different packages.